

# **"Business Changes and Challenges in the Competitive Semiconductor Industry"**

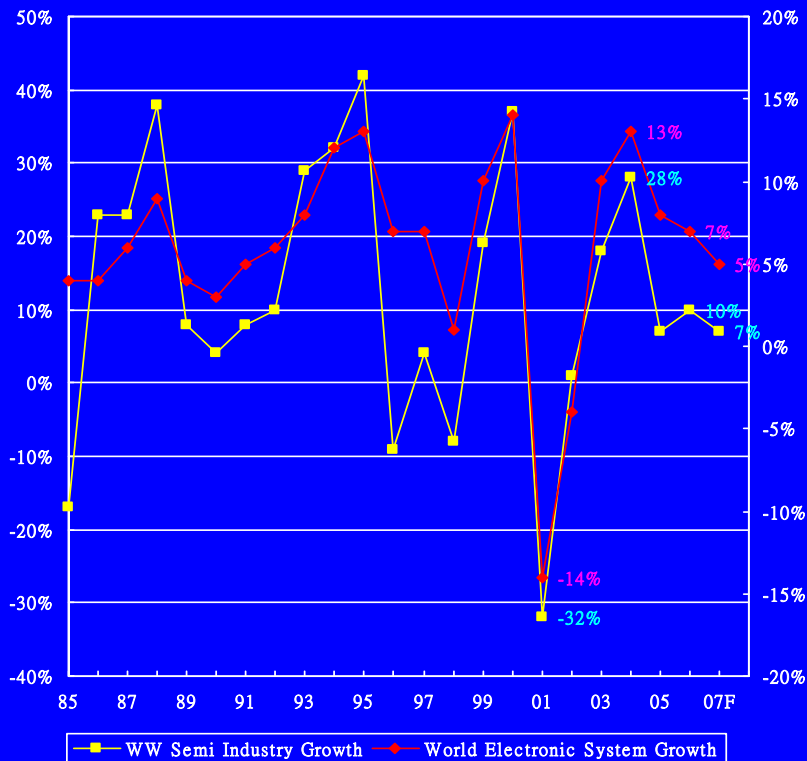
Allen C.-H. Wu  
Syntronix Corporation  
June 29 2007

# Outline

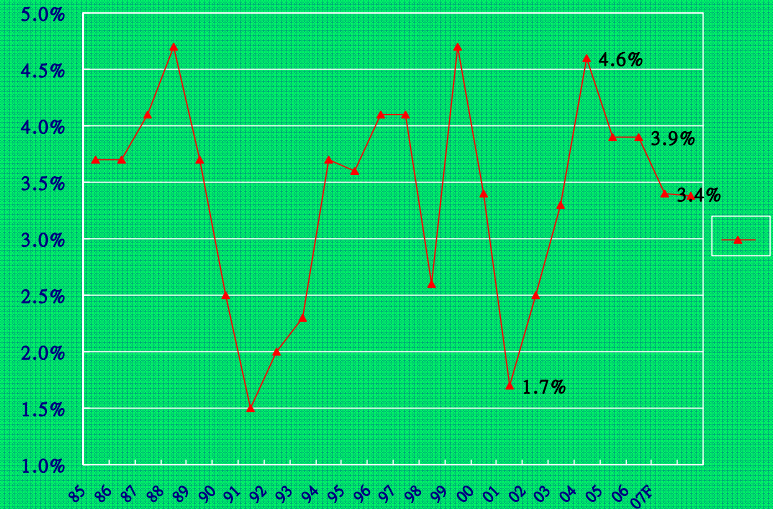
- Induction to Semiconductor Business
- Semiconductor Industry Trend
- Electronic-Product Supply Chain
- DRAM Business Trend
- ASSP/ASIC Business Trend

# Worldwide GDP Changes vs. Electronic System Growth/Semiconductor Industry Growth

Electronic System Growth/Semi Industry Growth



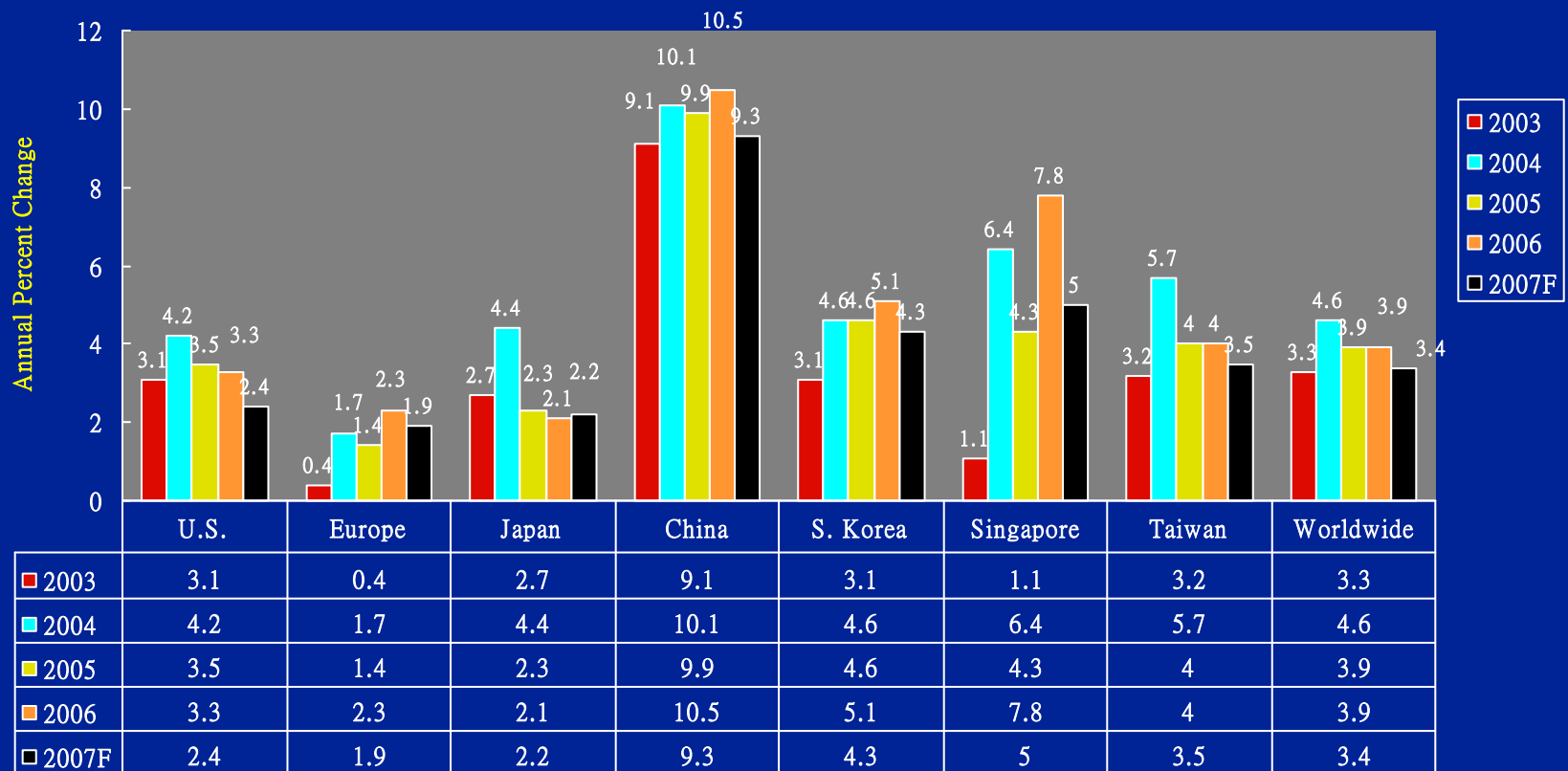
Worldwide GDP Change



Source: IC-Insights(2007/02); ITRI/IEK(2007/03)

# GDP by Nation

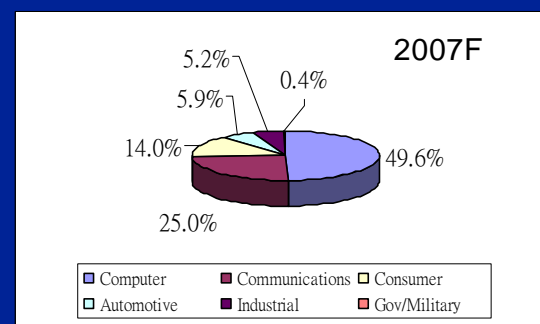
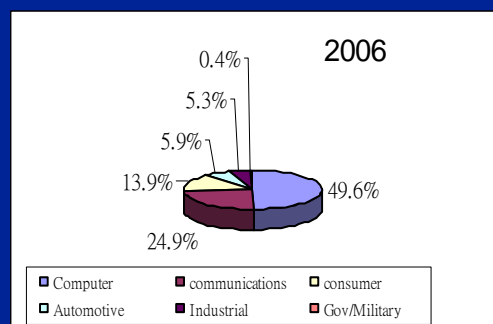
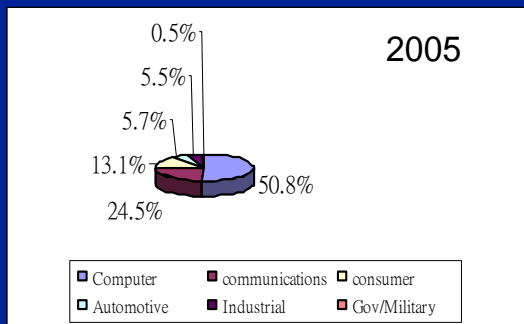
## 2003-2007 GDP Trends



Source: IC-Insights(2007/02); ITRI/IEK(2007/03)

# Electronic System Semiconductor Content

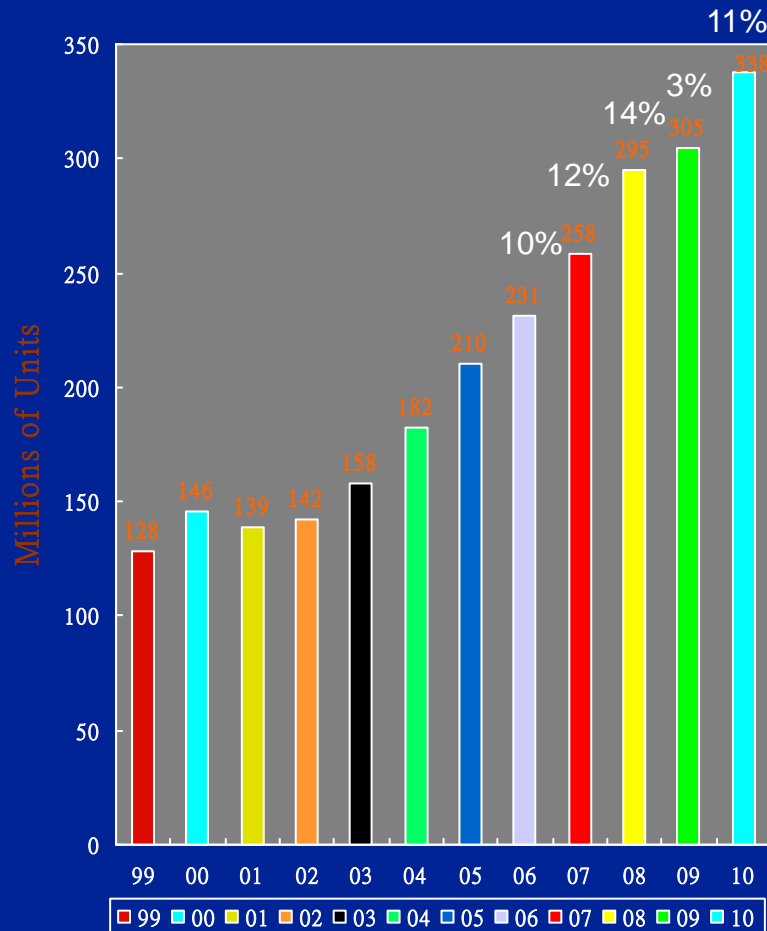
| System Type    | 2005  | % of Total | 2006  | % of Total | 2007  | % of Total |
|----------------|-------|------------|-------|------------|-------|------------|
| Computer       | 97.9  | 50.8%      | 103.6 | 49.6%      | 110.5 | 49.6%      |
| Communications | 47.2  | 24.5%      | 52.1  | 24.9%      | 55.7  | 25.0%      |
| Consumer       | 25.2  | 13.1%      | 29.1  | 13.9%      | 31.1  | 13.9%      |
| Automotive     | 10.9  | 5.7%       | 12.3  | 5.9%       | 13.2  | 5.9%       |
| Industrial     | 10.6  | 5.5%       | 11.0  | 5.2%       | 11.5  | 5.2%       |
| Gov/Military   | 0.9   | 0.5%       | 0.9   | 0.4%       | 0.9   | 0.4%       |
| Total          | 192.8 | 100.0%     | 209.0 | 100.0%     | 223.0 | 100.0%     |



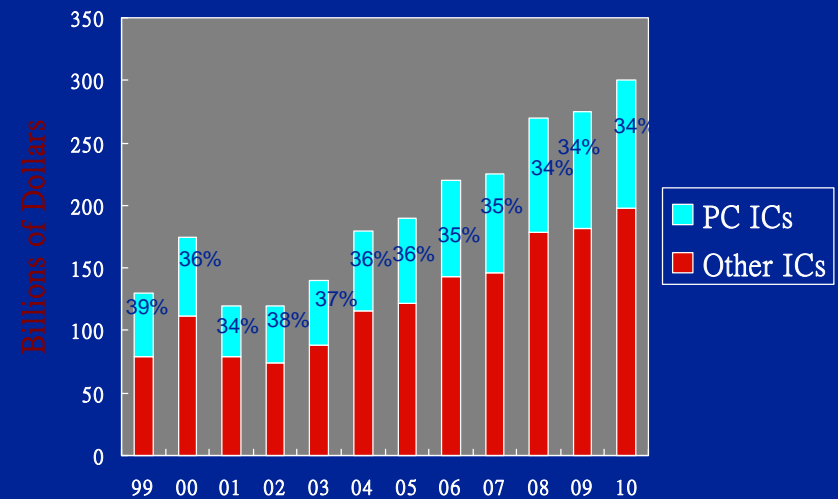
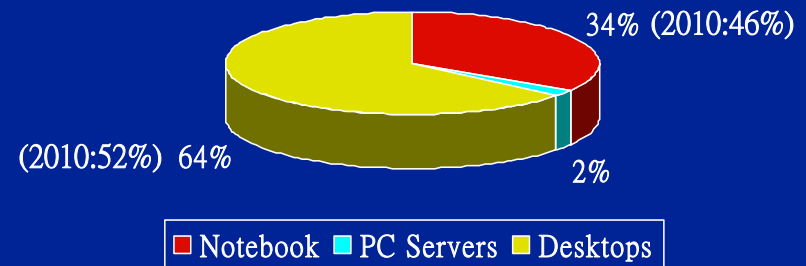
Source: IC-Insights(2007/02); ITRI/IEK(2007/03)

# Worldwide PC Shipments

## Worldwide PC Unit Shipments

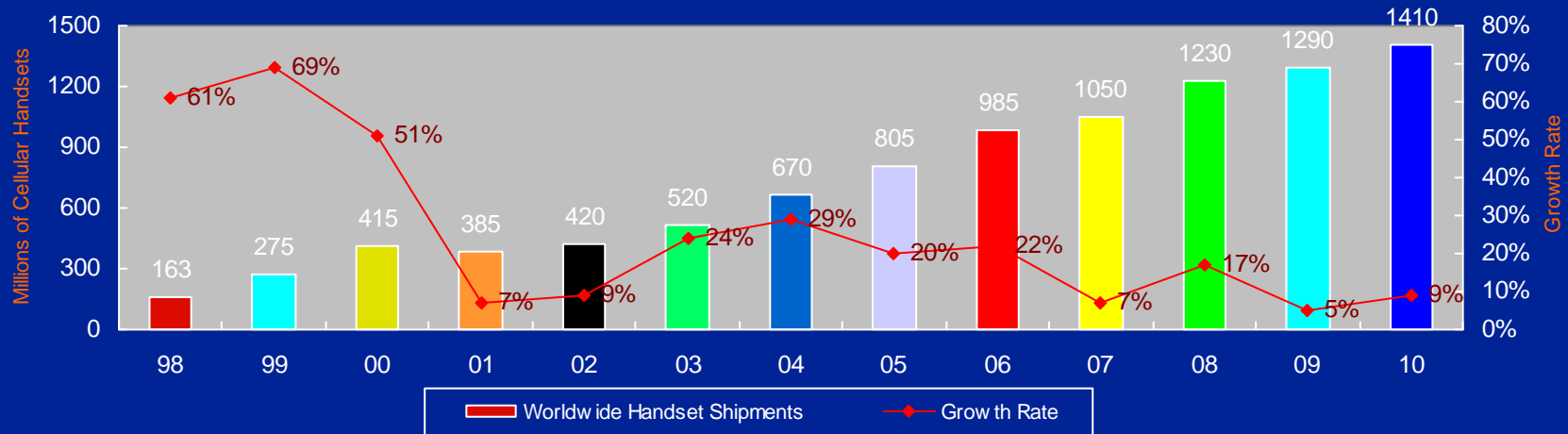


## 2006 PC Unit Shipment Estimate by System Type



Source: IC-Insights(2007/02); ITRI/IEK(2007/03)

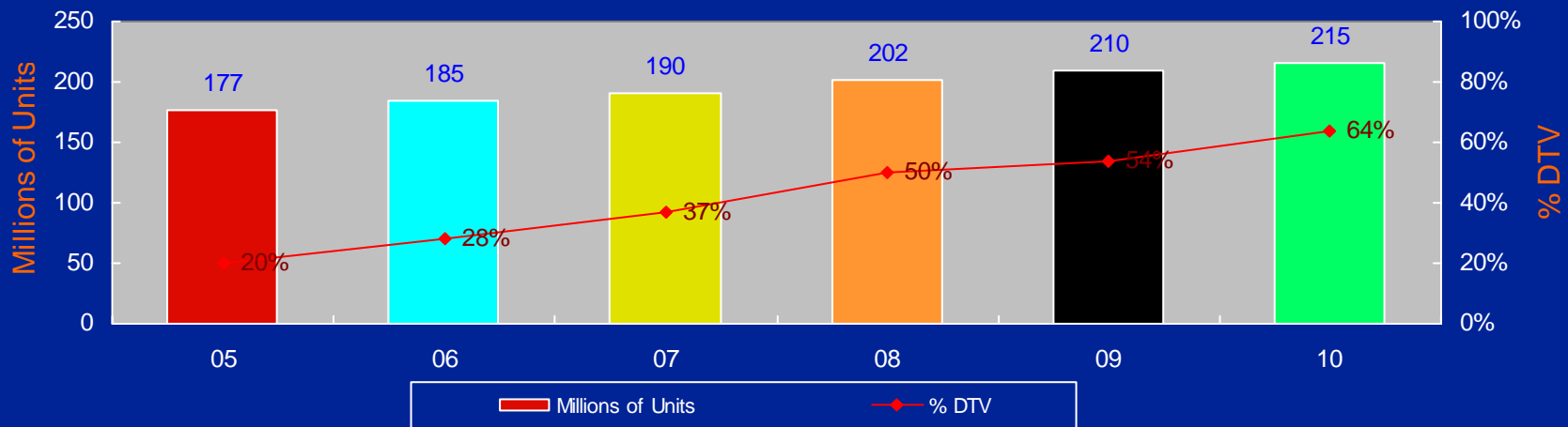
# Mobile Phone Shipments



- New ultra-low-cost phone demands for China/India/Africa:
  - ◆ 2006: 7%
  - ◆ 2010: 41%
- Camera Phones:
  - ◆ 2006: 53% (mainly <2M)
  - ◆ 2010: 78% (mainly >2M)
- 2G/2.5G GSM/GPRS/3G
  - ◆ 2006: 12%/67%/21%
  - ◆ 2010: 2%/59%/39%

Source: IC-Insights(2007/02); ITRI/IEK(2007/03)

# Worldwide TV Units Shipments



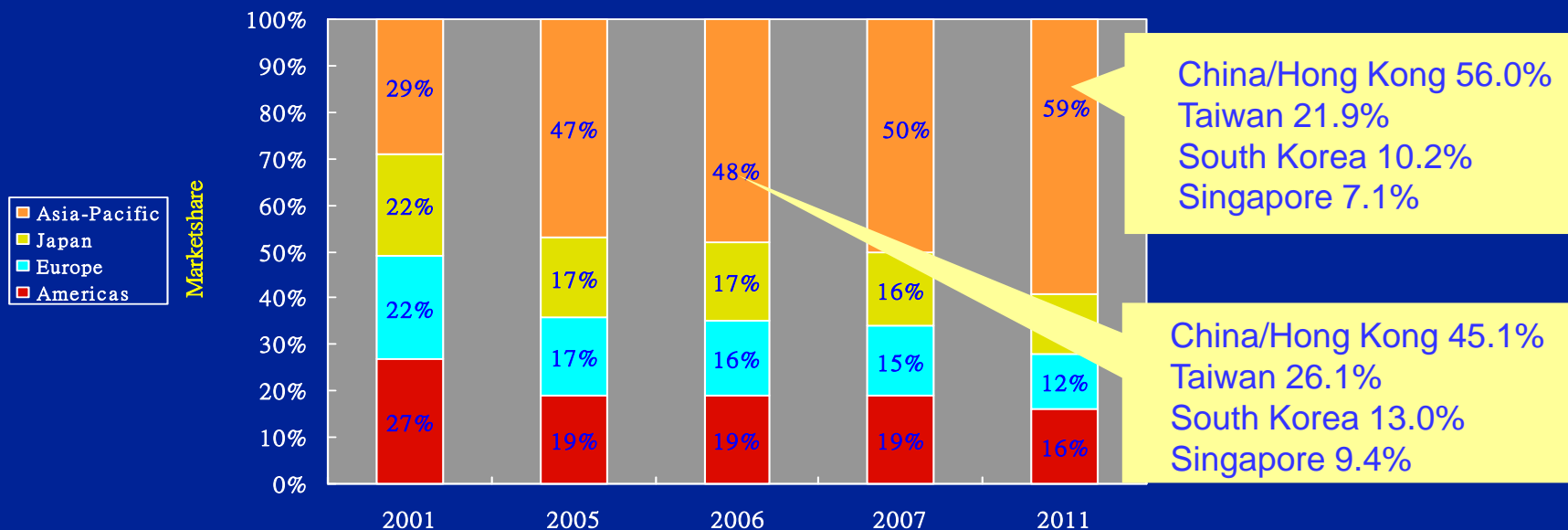
- 2006: DTV => 5M units/28% ( 77% LCD)
- 2010: DTV => 64% ( 84% LCD)
- 2007: DTV => 37% growth

Source: IC-Insights(2007/02); ITRI/IEK(2007/03)

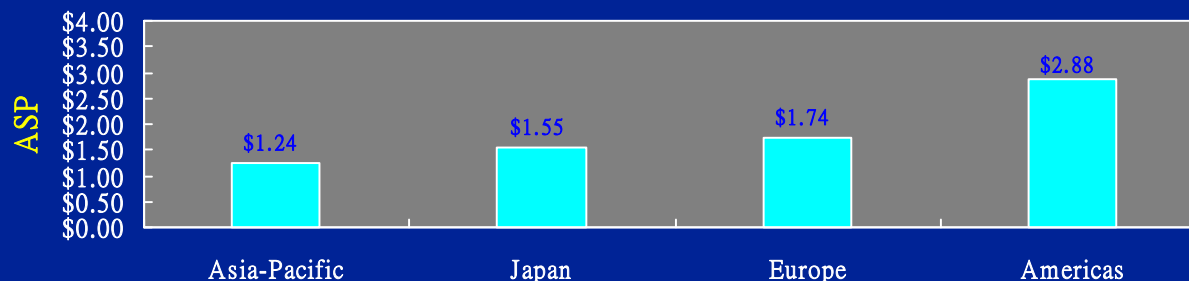


# Worldwide IC Market by Region

Worldwide IC Market by Region(2001-2011)

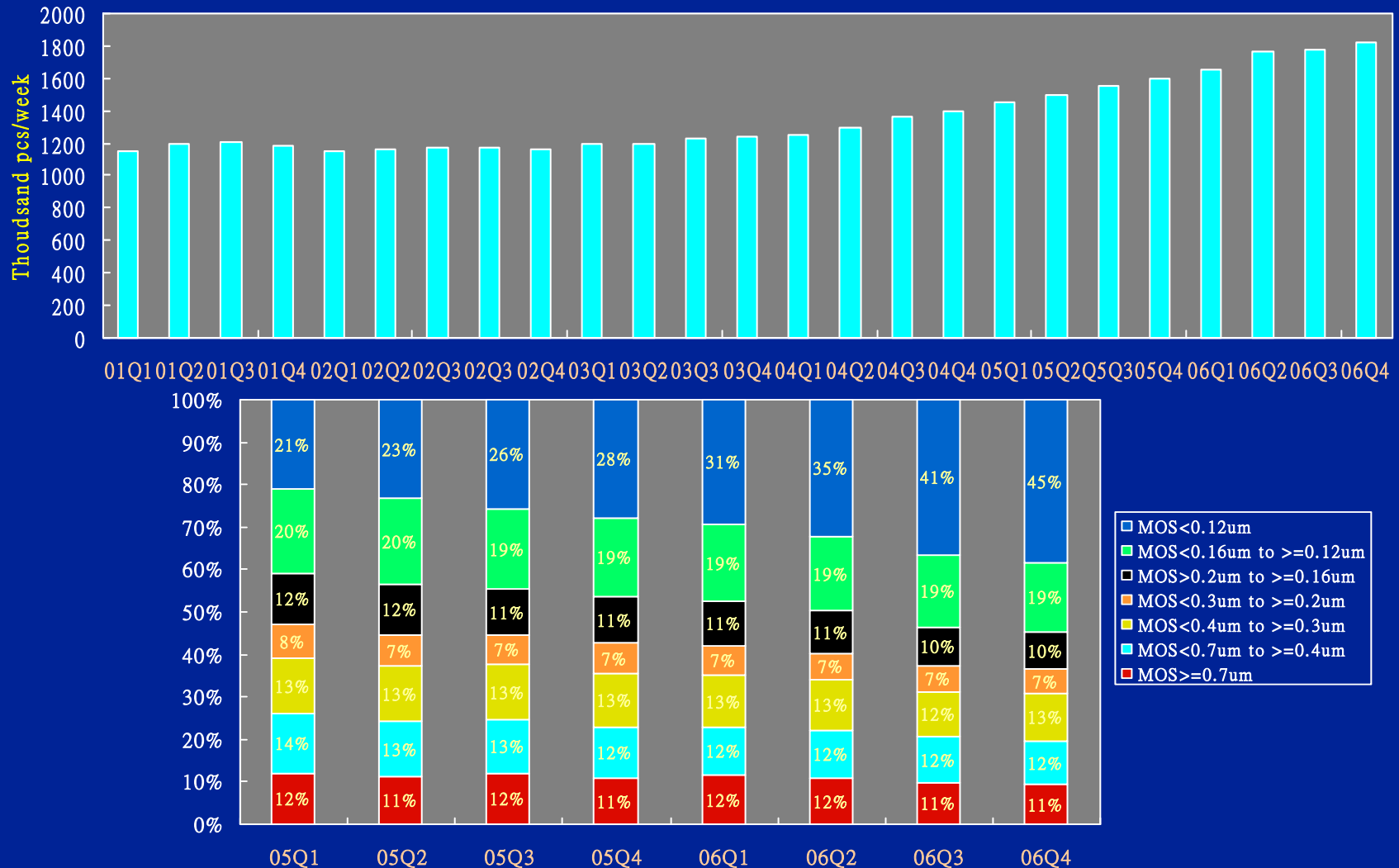


2006 Regional Market IC Average Selling Prices



Source: IC-Insights(2007/02); ITRI/IEK(2007/03)

# Worldwide Semiconductor Capacities



Source: SICAS(2007/03); ITRI/IEK(2007/03)

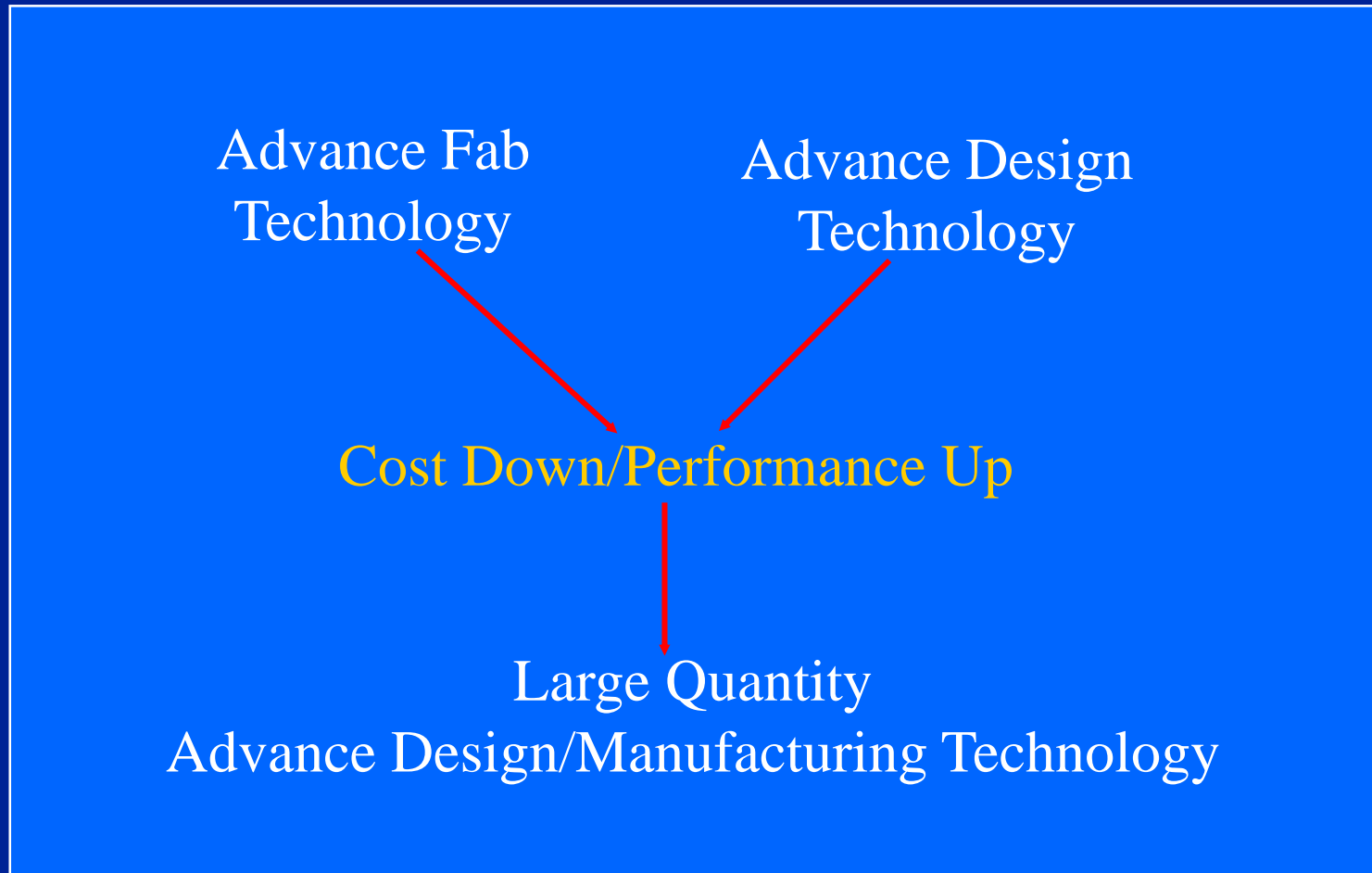
# Outline

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# Semiconductor Industry Trend (I)

- Moore's law
- Continuous advance technology developments
- Cost down

# Semiconductor Industry Trend (II)



# Semiconductor Industry Trend (III)

- Does Moore's law still the driver?
  - ◆ What types of products (and the total demands) need technology of 90nm & below?
  - ◆ How many players can afford it?

# Semiconductor Industry Trend (IV)

- Technology Driven → Market Driven
  - ◆ Product competitiveness by migrating designs into advanced process technologies (more # of dies + more features => lower cost)!
  - ◆ Technology barrier among players is narrowing
  - ◆ What are the main differential points between players? TTM, Cost & Key IPs.

# Semiconductor Industry Trend (V)

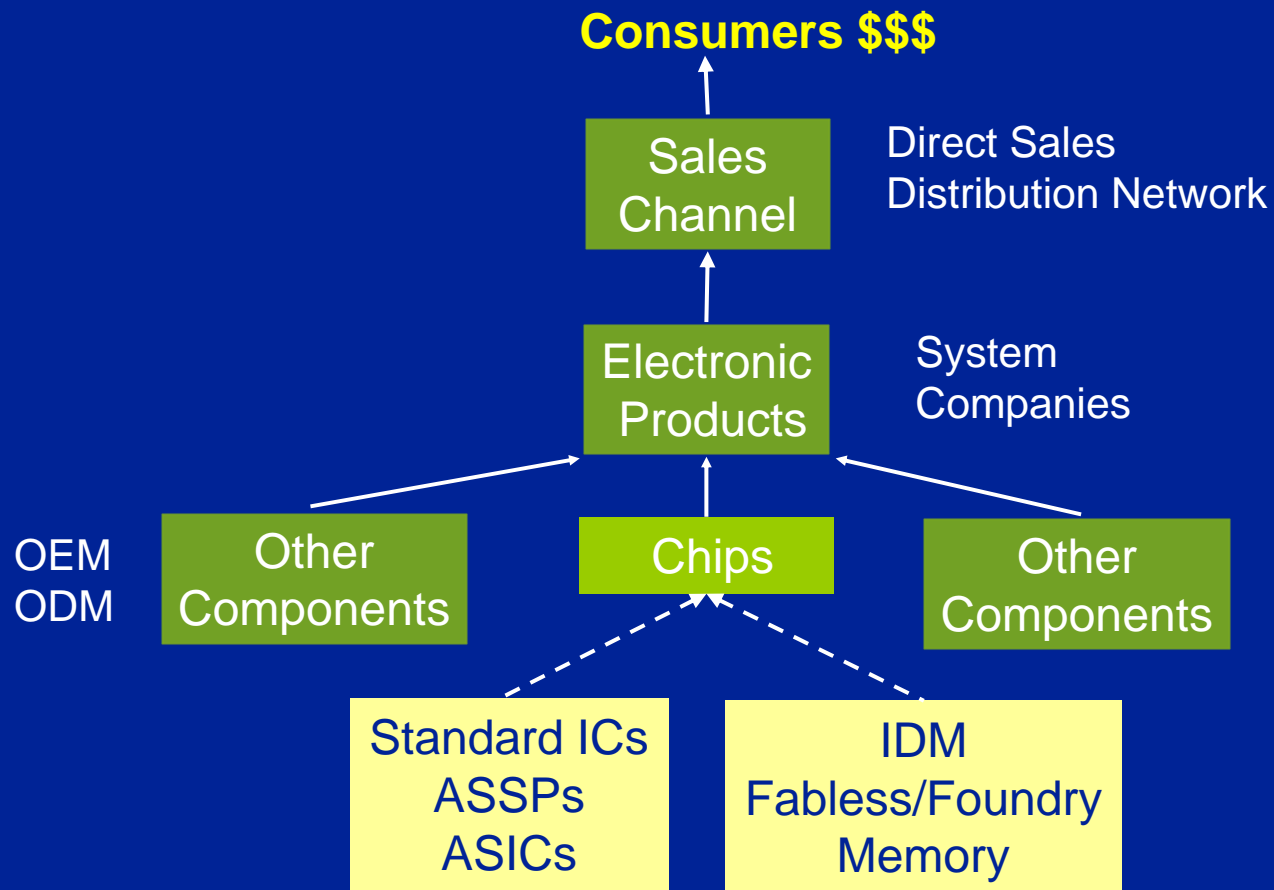
- Is semiconductor industry entering the traditional industry era???
- ◆ Mature technologies + limited applications => many players can enter the ball game and compete in the same market
- ◆ Profit margin drops
- ◆ Slow growth
- ◆ The bigger is getting bigger



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# Electronic-Products Supply Chain



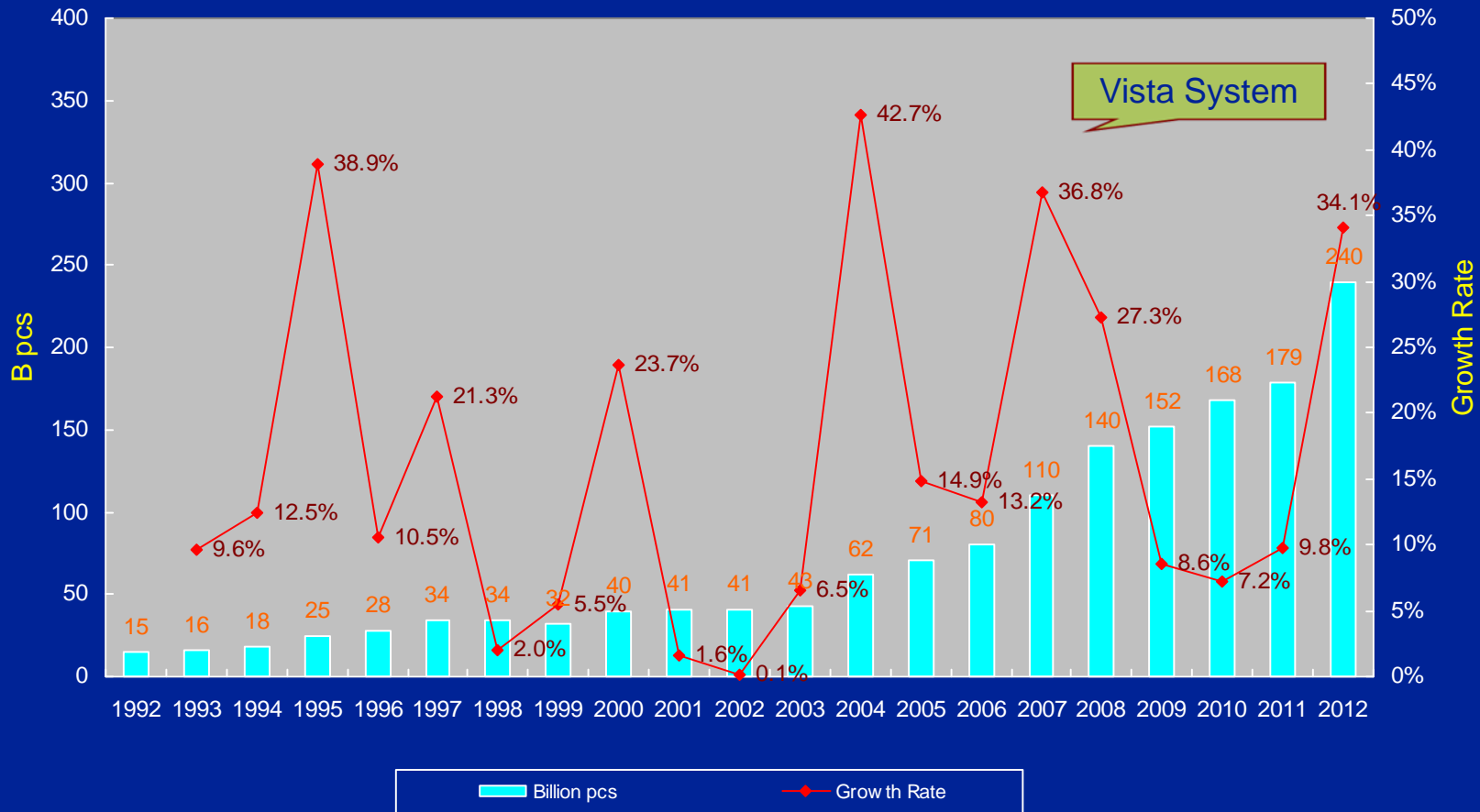
# Three Major Chip Categories

- Standard ICs
  - ◆ CPU: (INTEL:INTEL:INTEL)
  - ◆ Memories: Cost is the key!
- ASSPs /ASICs
  - ◆ Design-in capability is the key!

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# Worldwide DRAM Market

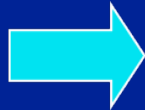


Source: Gartner(2007/02); ITRI/IEK(2007/03)

# Worldwide DRAM Market Share

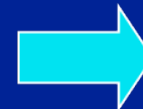
|              | 1987  | Market Share |
|--------------|-------|--------------|
| Total Market | 2,902 |              |
| NEC          | 469   | 16.2         |
| Fujitsu      | 409   | 14.1         |
| Toshiba      | 379   | 13.1         |
| TI           | 320   | 11.0         |
| Mitsubishi   | 292   | 10.1         |
| Hitachi      | 279   | 9.6          |
| Samsung      | 153   | 5.3          |
| OKI          | 152   | 5.2          |

#1 Japan; #2 USA; #3 Korea



|              | 1992  | Market Share |
|--------------|-------|--------------|
| Total Market | 8,765 |              |
| Samsung      | 1,192 | 13.6         |
| Toshiba      | 1,123 | 12.8         |
| NEC          | 894   | 10.2         |
| Hitachi      | 824   | 9.4          |
| TI           | 667   | 7.6          |
| Mitsubishi   | 628   | 7.2          |
| Fujitsu      | 547   | 6.2          |
| LG Semicon   | 513   | 5.9          |

#1 Samsung



|              | 2004  | Market Share |
|--------------|-------|--------------|
| Total Market | 26317 |              |
| Samsung      | 8119  | 30.9         |
| Hynix        | 4288  | 16.3         |
| Micron       | 4167  | 15.8         |
| Infineon     | 3499  | 13.3         |
| Elpida       | 1569  | 6.0          |
| Nanya        | 1186  | 4.5          |
| PowerChip    | 1128  | 4.3          |
| ProMOS       | 900   | 3.4          |

#1 Korea; #2 Taiwan  
USA/EU/Japan only 1 company left

| 2005 Rank | 2006 Rank |           | 2005  | 2006  | 2005-2006 Change | 2006 Share |
|-----------|-----------|-----------|-------|-------|------------------|------------|
| 1         | 1         | Samsung   | 8,020 | 9,834 | 22.6%            | 28.7%      |
| 2         | 2         | Hynix     | 4,111 | 5,644 | 37.3%            | 16.5%      |
| 4         | 3         | Qimonda   | 3,181 | 5,370 | 68.8%            | 15.7%      |
| 3         | 4         | Micron    | 3,867 | 3,697 | -4.4%            | 10.8%      |
| 5         | 5         | Elpida    | 1,784 | 3,489 | 95.6%            | 10.2%      |
| 6         | 6         | Nanya     | 1,440 | 2,111 | 46.6%            | 6.2%       |
| 7         | 7         | Powerchip | 1,027 | 1,479 | 44.0%            | 4.3%       |
| 8         | 8         | ProMOS    | 871   | 1,462 | 67.9%            | 4.3%       |

- ◆ Korea #1, world market share 45.2% (Hynix: ProMOS foundry)
- ◆ Taiwan #2, world market share increases: by products 18%, by capacity 25%
- ◆ Qimonda 15.7% (Nanya: foundry)
- ◆ Micron world market share drops to 10.8%
- ◆ Elpida 10.2% (PSC: foundry)

Source: Dataquest(2007/02); ITRI/IEK(2007/03)

# Worldwide DRAM Strategy Changes

- Terminated the business/Sold the fab
  - ◆ TI, IBM, Toshiba
  - ◆ Vanguard, Mosel, Winbond
- Established New Companies
  - ◆ Elpida (by NEC, Hitachi, Mitsubishi)
  - ◆ Rexchip (by Elpida, PSC)
- Merged, Purchased fab
  - ◆ Micron (TI, Toshiba)
- Capacity & Technology Cooperation
  - ◆ Infineon: Nanya, Winbond, SMIC
  - ◆ Elpida: PSC, SMIC
  - ◆ Hynix: ProMOS
- New Players
  - ◆ SMIC, Grace

# Worldwide DRAM Supply and Demand

## ◆ Demand : # of 12" fabs

|                               | 2006  | 2007  | 2008  | 2009 | 2010 | 2011 | 2012  |
|-------------------------------|-------|-------|-------|------|------|------|-------|
| Worldwide DRAM demand (B pcs) | 79    | 110   | 141   | 154  | 166  | 181  | 210   |
| Growth rate                   | 17.8% | 38.3% | 28.8% | 8.8% | 7.7% | 9.1% | 16.3% |
| #12" fabs (40k wafers/month)  | 23    | 31    | 35    | 40   | 47   | 52   | 57    |

## ◆ Supplier : # of 12" fabs

|                   | 2006 | 2007 | 2008 | 2009 | 2010 | 2011 | 2012 |
|-------------------|------|------|------|------|------|------|------|
| Samsung           | 4    | 5    | 6    | 8    | 10   | 12   | 14   |
| Hynix             | 1    | 2    | 2    | 3    | 3    | 4    | 4    |
| Micro             | 1    | 2    | 2    | 2    | 2    | 2    | 2    |
| Qimonda           | 2    | 2    | 2    | 2    | 3    | 3    | 3    |
| Elpida            | 1    | 1    | 1    | 2    | 2    | 2    | 2    |
| SMIC              | 1    | 2    | 3    | 3    | 3    | 3    | 3    |
| Subtotal          | 10   | 14   | 16   | 20   | 23   | 26   | 28   |
| PSC+Rexchip       | 3    | 4    | 5    | 8    | 11   | 12   | 13   |
| Nanya+Inotera     | 1    | 3    | 4    | 5    | 5    | 6    | 6    |
| ProMOS            | 2    | 3    | 4    | 5    | 6    | 7    | 7    |
| Winbond           | 1    | 1    | 1    | 1    | 1    | 1    | 1    |
| 12" fab in Taiwan | 7    | 11   | 14   | 19   | 23   | 26   | 27   |
| Total             | 17   | 25   | 30   | 39   | 46   | 52   | 55   |



# DRAM Business Trend

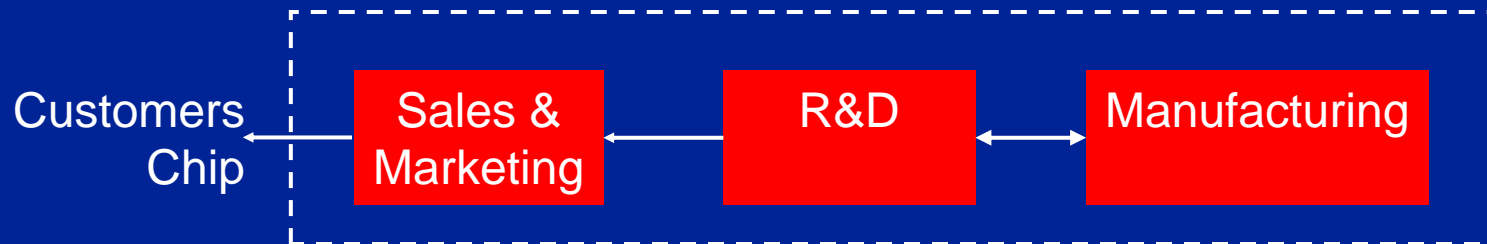
- A typical commodity business
- Pricing is the key to success
- Keep pushing cost-driven advanced design and manufacturing technologies
- Market-driven penny-pinch cost-down strategy on the entire supply chain

# Outline

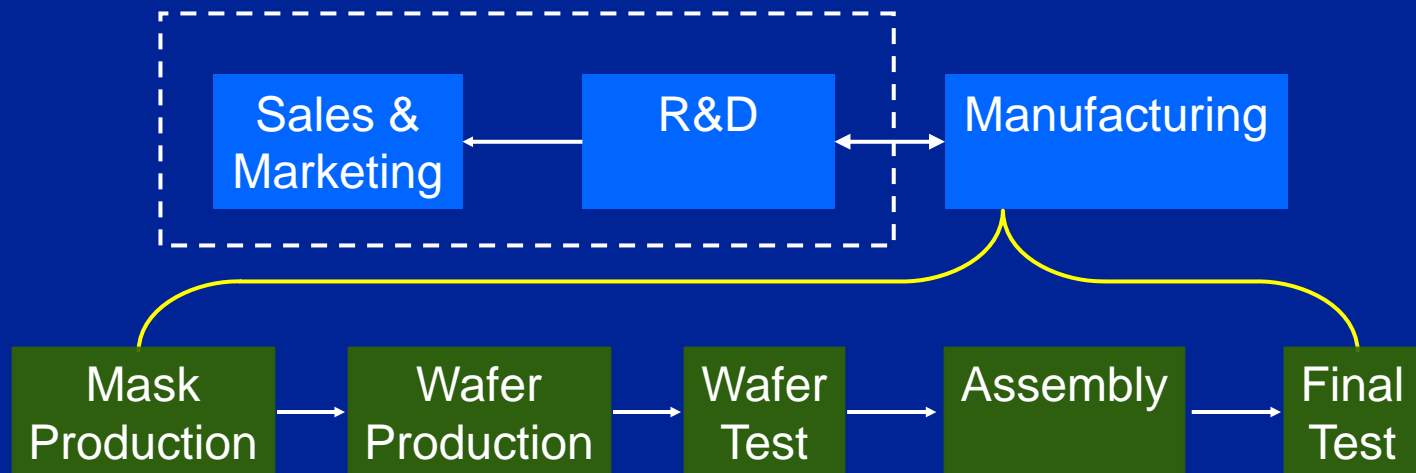
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# IDM v.s. Fabless/Foundry

## IDM



## Fabless / Foundry



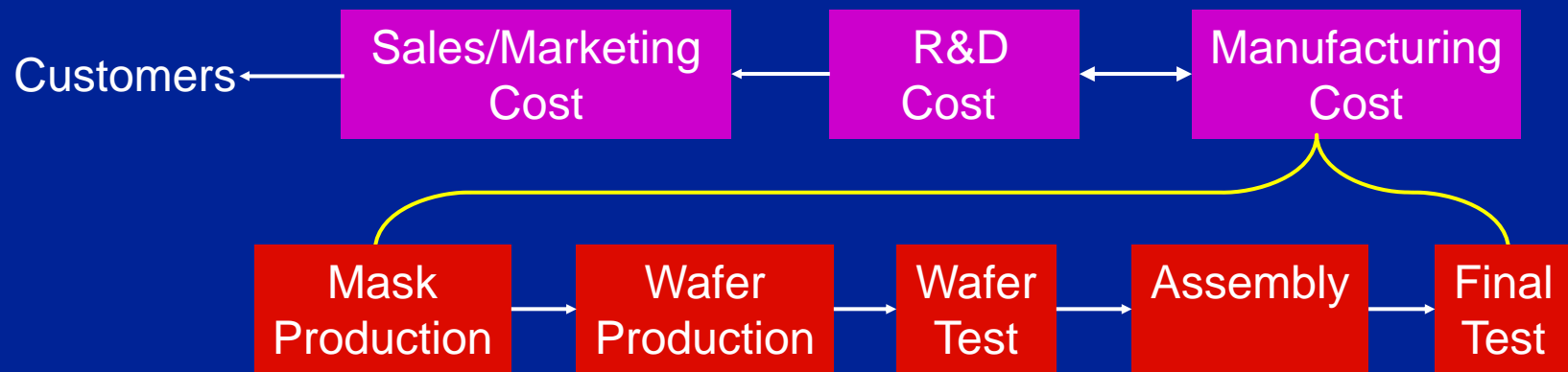
# Product Trend

- Two camps: luxury and low-cost items
- Lack of killer applications
- 3C(Computer, Communication, Consumer) integration: what's next?
- Hardware may not be the profit source, software and service will be the main profit sources!
  - ◆ Free phone + service
  - ◆ Cheap game box + software
  - ◆ Scanner + suppliers

# Cost-Driven ASIC/ASSP Sales Strategy

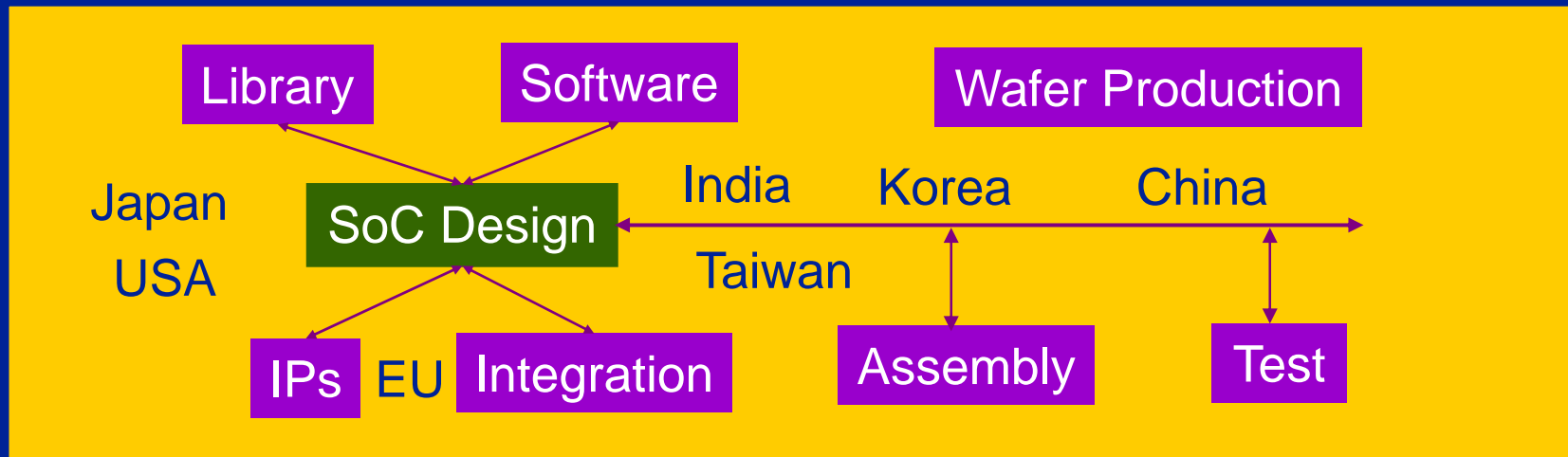
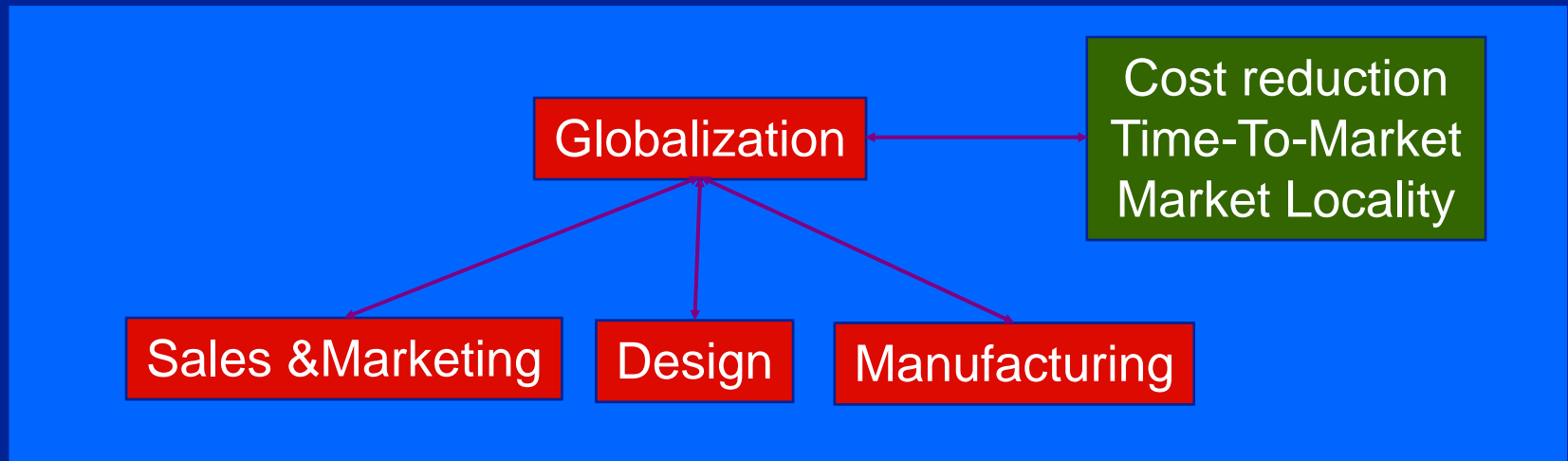
- Reducing the overall cost by squeezing the entire supply chain
- Establishing alliances and partnerships in order to guarantee capacity and pricing
- Locality market-driven sales strategy
  - => China: total solution based sales strategy
  - => Japan: multiple agent and distribution channels problem!
- Strong design-in capability and service

# Cost Structure



Sales Price = Direct Cost+ Indirect Cost + Profit

# Globalization Cooperation Strategy



# Design, Manufacturing and R&D Costs of 45nm/32nm Process

|             | 45nm      | 32nm     |
|-------------|-----------|----------|
| Fab         | \$3B      | \$5B-10B |
| Process R&D | \$2.4B    | \$3B     |
| Design      | \$20M-50M | \$75M    |
| Mask        | \$9M      | NA       |

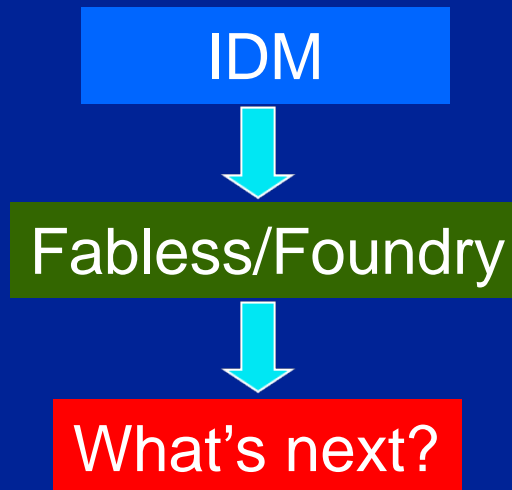
Source: EE Times, Synopsys, VLSI Research



# Technology Trend

- Deep submicron technology(65nm up), R&D cost is very expensive
  - ◆ Co-development with foundry companies
  - ◆ Own technology
- Chip development cost is getting higher and higher
  - ◆ Only the top players will survive
  - ◆ Chip development strategy is changing

# Semiconductor Industry Evolution



“ IC Industry in midst of fundamental change”  
Wofgang Ziebart-Infineon CEO

# Business Trend

- Cost-down strategy
- More strategic partnerships
- Market Driven: Name-brand (Luxury items) and  
Non-Name-brand (Low-cost items)
- Moving toward traditional industry

# Thank You!